

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	394	interposer with capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:07
S2	355	S1 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:03
S3	276	S2 and (bump solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:33
S4	149	S2 and (bump solder)	USPAT	OR	ON	2005/08/07 15:33
S5	3	("5903050"   "5937493"   "6384468").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:34
S6	48	("5519576"   "5672909"   "5691568").PN. OR ("5903050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:35
S7	35	("4225468"   "4300115"   "4332341"   "4626804"   "4654628"   "4658234"   "4712161"   "4945399"   "5216404"   "5379190"   "5539186"   "5557502"   "5621619"   "5629838"   "5635767"   "5636099"   "5661450"   "5726485"   "5729438"   "5745334"   "5760662"   "5796587"   "5870274"   "5903050"   "5923077"   "5977863"   "6005777"   "6097277"   "6103146"   "6124634").PN. OR ("6326677").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:38
S8	61	teflon with elasticity with modul\$5	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:39
S9	0	teflon near2 "Young's" adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:40
S10	0	teflon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:40

S11	121220	teflon wiht Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:43
S12	16	teflon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:40
S13	857	silicon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:43
S14	68	silicon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:44
S15	17	("6222246").URPN.	USPAT	OR	ON	2005/08/07 15:47
S16	44335	layer near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:55
S17	18533	S16 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:50
S18	23	interposer with S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:03
S19	31886	film near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:02
S20	20	interposer with S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:55
S21	21900	substrate near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:02

S22	6306	substrate with S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:03
S23	3545	S22 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:03
S24	186	interposer with capacit\$5	USPAT	OR	ON	2005/08/07 16:40
S25	0	capacitive adj layer with interposer	USPAT	OR	ON	2005/08/07 16:40
S26	0	capacitive adj layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:40
S27	2	capacitive near2 layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:16
S28	53	("4202007"   "4322778"   "4328530"   "4349862"   "4489364"   "4688151"   "4744008"   "4803595"   "4811082"   "4866507"   "4926241").PN. OR ("5177594"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 16:47
S29	1	"5177594".PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 16:47
S30	1	S29 AND capac\$8	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 16:47
S31	53	("4202007"   "4322778"   "4328530"   "4349862"   "4489364"   "4688151"   "4744008"   "4803595"   "4811082"   "4866507"   "4926241").PN. OR ("5177594"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 16:58
S32	19937	motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:17

S33	27	motherboard with PCB WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:18
S34	235	motherboard WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:19
S35	91	motherboard WITH interposer	USPAT	OR	ON	2005/08/07 18:21
S36	0	motherboard WITH leve	USPAT	OR	ON	2005/08/07 18:21
S37	321	motherboard WITH level	USPAT	OR	ON	2005/08/07 18:22
S38	0	mother adj board WITH last with level	USPAT	OR	ON	2005/08/07 18:22
S39	8	mother adj board WITH last	USPAT	OR	ON	2005/08/07 18:23
S40	1364	motherboard and "257"/\$.ccls.	USPAT	OR	ON	2005/08/07 18:24
S41	174	S40 and interposer	USPAT	OR	ON	2005/08/07 18:24